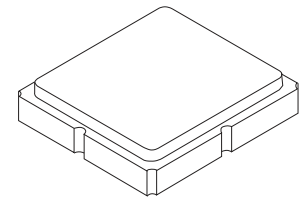


RF3626E

**315 MHz
SAW Filter**



**SM3030-6 Case
3.0 x 3.0**

- **Ideal Front-End Filter for European Wireless Receivers**
- **Low-Loss, Coupled-Resonator Quartz Design**
- **Simple External Impedance Matching**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**
- **AEC-Q200 Qualified**

Rating	Value	Units
Input Power Level	13	dBm
DC Voltage	0	VDC
Storage Temperature	-40 to +105	°C
Operable Temperature Range	-40 to +105	°C
Solder Reflow Temperature 5 Cycles Maximum)	260°C for 10 seconds	

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency	f_c			315		MHz
Minimum Insertion Loss	IL_{min}	Including loss of matching elements 314.615 to 315.385 MHz Excluding loss in matching elements 314.615 to 315.385 MHz		2.0	3.0	dB
				1.1	1.9	
Passband (relative to IL_{min})			314.615 to 315.385 MHz 314.52 to 315.48 MHz		2.0	
			2.5	3.0		
Attenuation (relative to IL_{min})						dB
10 to 140 MHz			66	71		
140 to 235 MHz			57	62		
235 to 300 MHz			44	49		
300 to 310 MHz			23	34		
310 to 313 MHz			9	14		
317 to 320 MHz			9	14		
320 to 325 MHz			15	20		
325 to 332 MHz			27	32		
332 to 352 MHz			36	41		
352 to 390 MHz			47	52		
390 to 1600 MHz			55	60		
1600 to 2500 MHz			50	55		
Package Size			SMD 3.0 X 3.0			mm
Lid Symbolization (Y=year WW=week S=shift)			5N, YWWS			

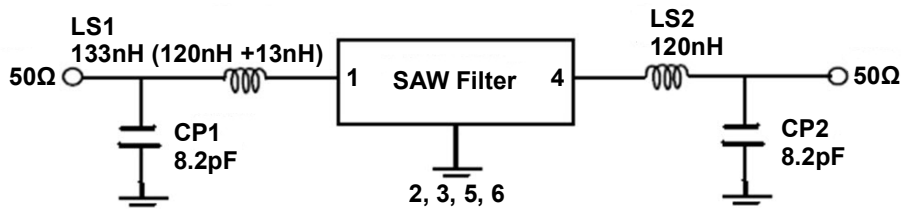


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

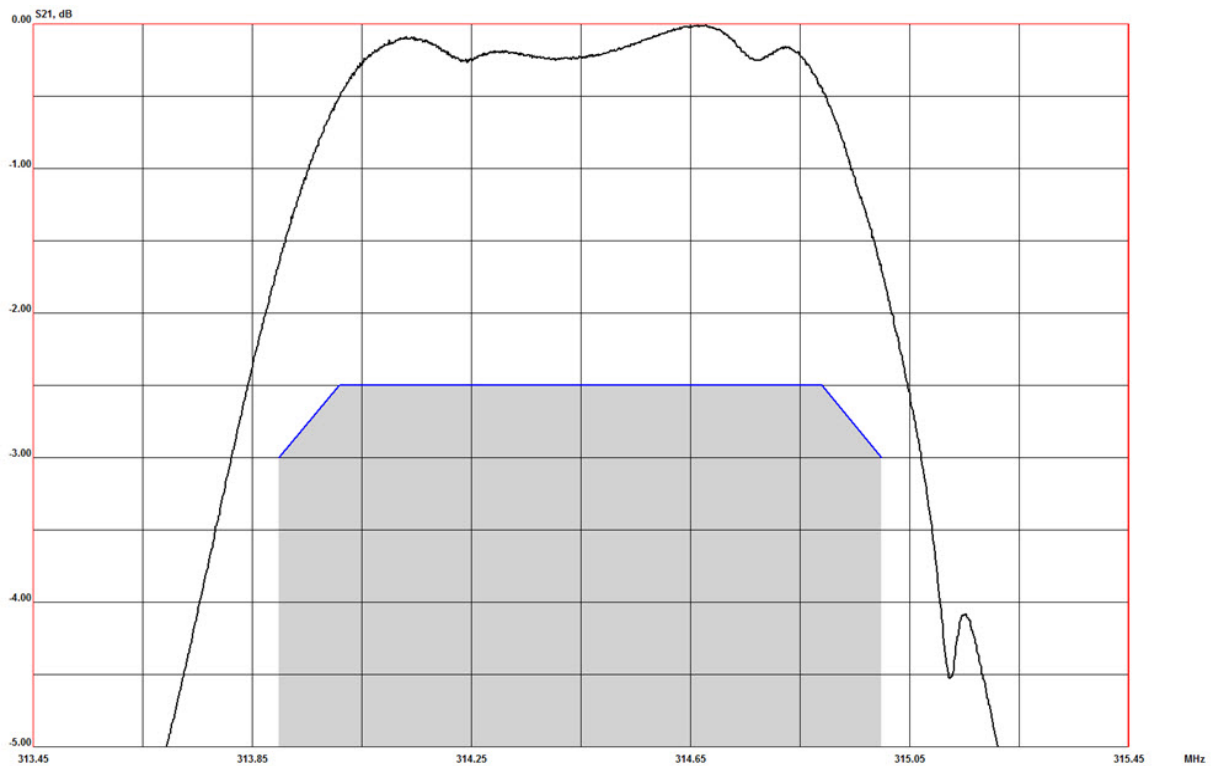
Measurement Circuit



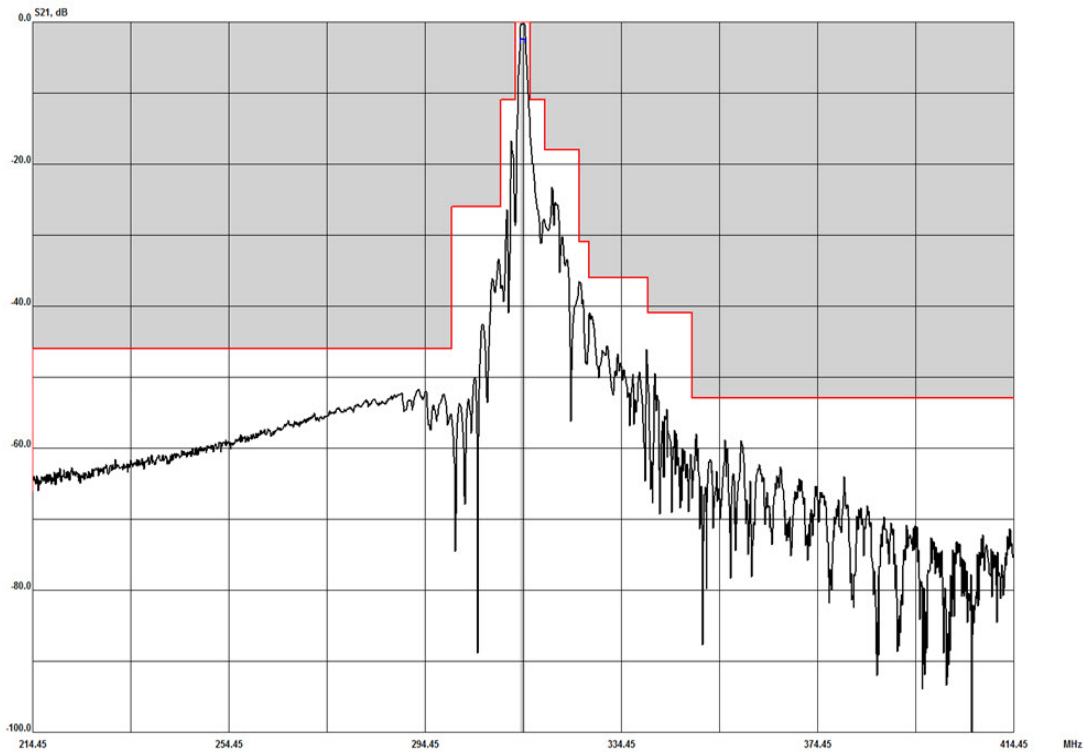
Pin	Connection
1	Input or Input Ground
2	Input Ground or Input
4	Output or Output Ground
5	Output Ground or Output
3, 6	Ground

Frequency Characteristics

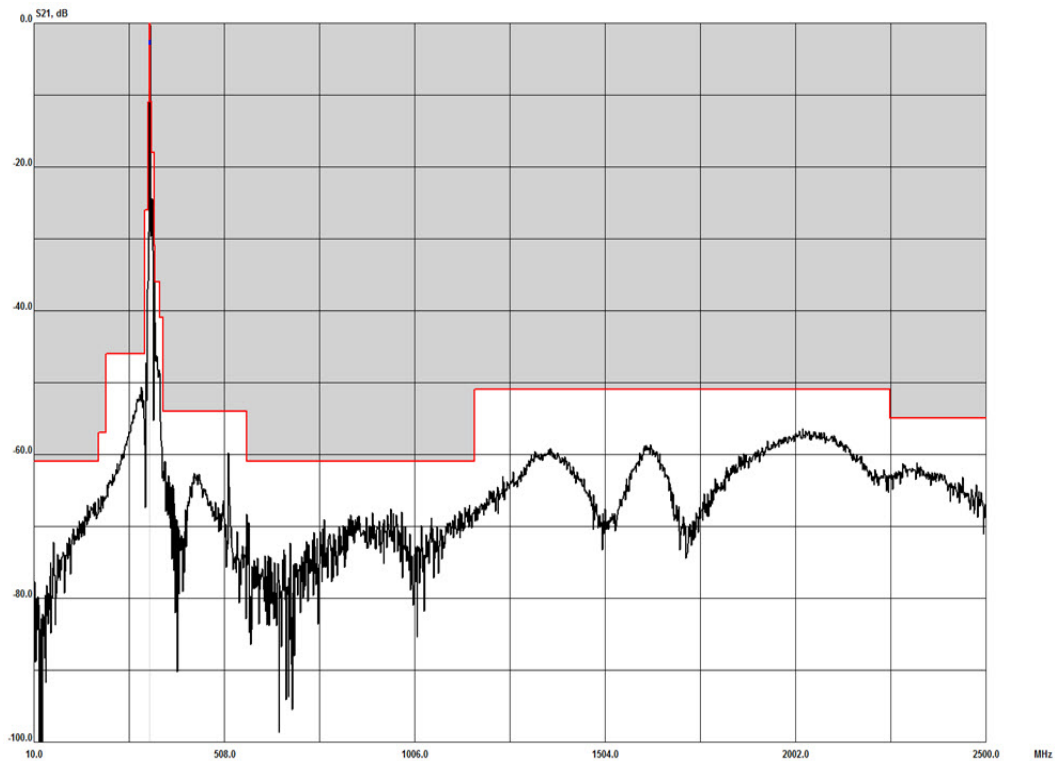
S21 Response: Span 2 MHz



S21 Response: Span 200 MHz

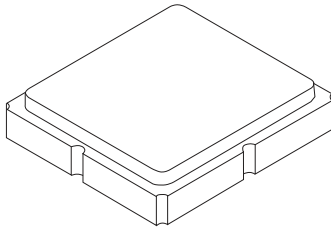


S21 Response: Span 10 MHz to 2.5 GHz



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

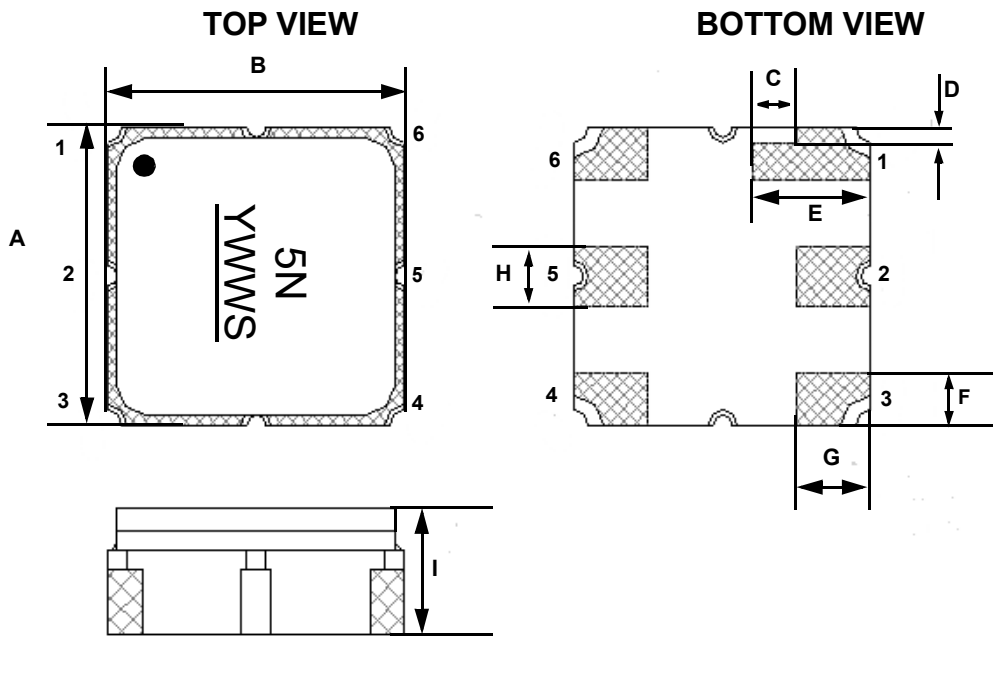


Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.85	3.00	3.15	0.112	0.118	0.124
B	2.85	3.00	3.15	0.112	0.118	0.124
C	-	0.45	-	-	0.177	-
D	-	0.15	-	-	0.005	-
E	1.05	1.20	1.35	0.041	0.047	0.053
F	0.38	0.53	0.68	0.014	0.020	0.026
G	0.60	0.75	0.90	0.023	0.029	0.035
H	0.55	0.60	0.65	0.021	0.023	0.025
I	-	-	1.40	-	-	0.055

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

